

PNA3W01L (PN307)

Silicon planar type

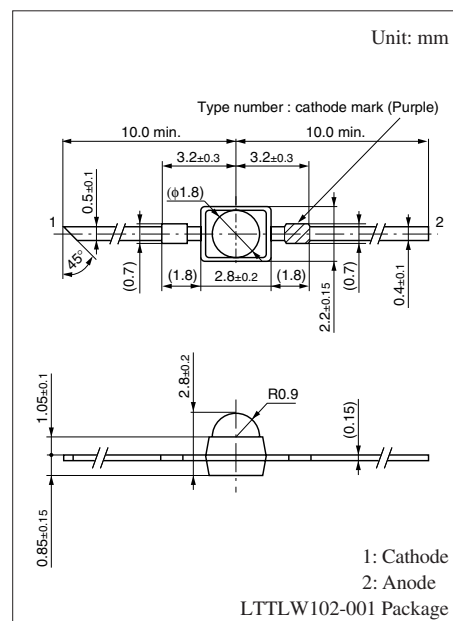
For optical control systems

■ Features

- High sensitivity, high reliability
- Peak emission wavelength matched with infrared light emitting diodes: $\lambda_p = 800 \text{ nm}$ (typ.)
- Double end type small size package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Power dissipation	P_D	10	mW
Operating ambient temperature	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +100	$^\circ\text{C}$



■ Electrical-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Dark current	I_D	$V_R = 10 \text{ V}$			50	nA
Photocurrent *1	I_L	$V_R = 10 \text{ V}, L = 1000 \text{ lx}$	5			μA
Peak emission wavelength	λ_p	$V_R = 10 \text{ V}$		800		nm
Rise time *2	t_r	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega$		50		ns
Fall time *2	t_f			50		ns
Rise time *2	t_r	$V_R = 10 \text{ V}, R_L = 100 \text{ k}\Omega$		5		μs
Fall time *2	t_f			5		μs
Half-power angle	θ	The angle from which photocurrent becomes 50%		24		$^\circ$

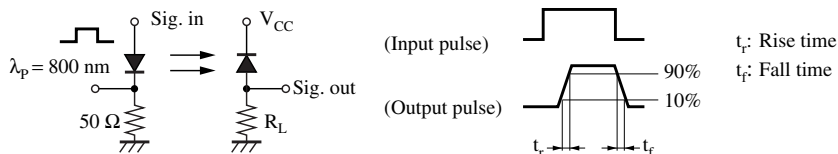
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.

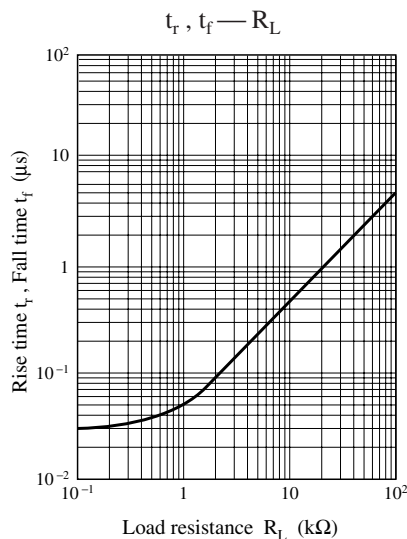
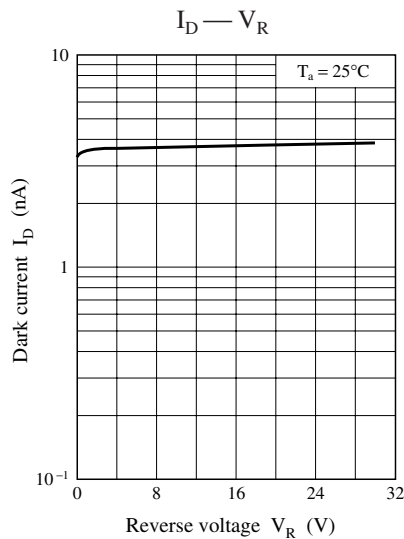
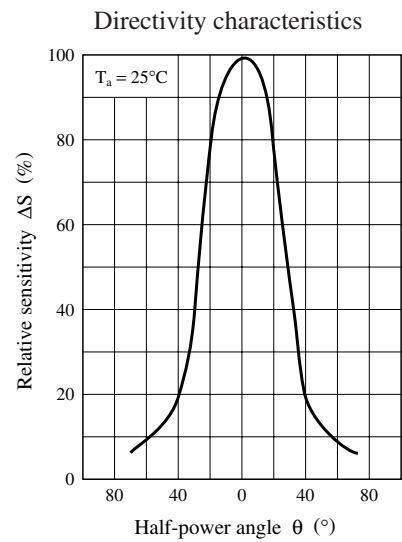
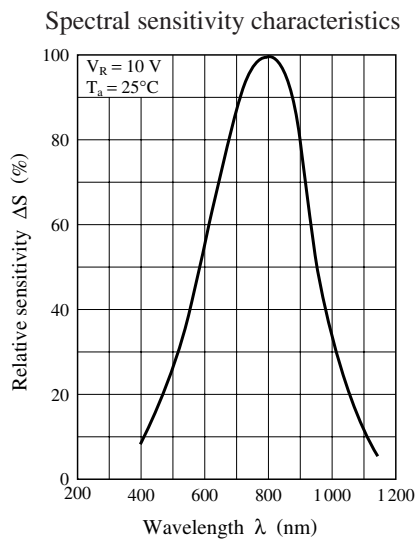
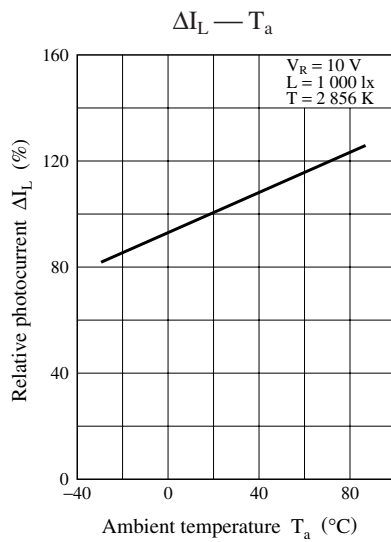
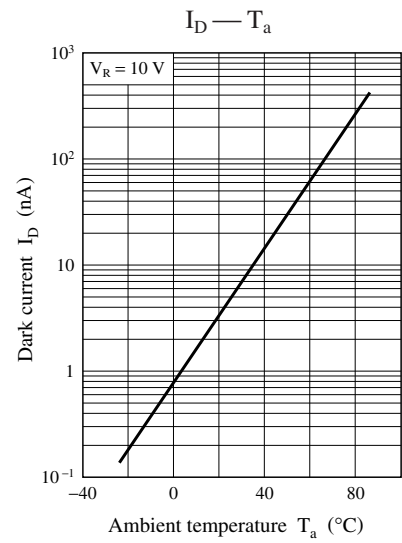
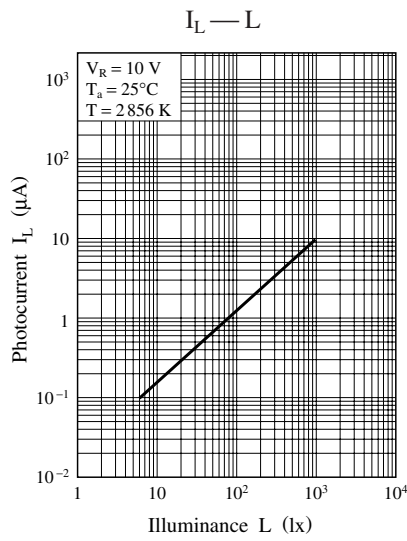
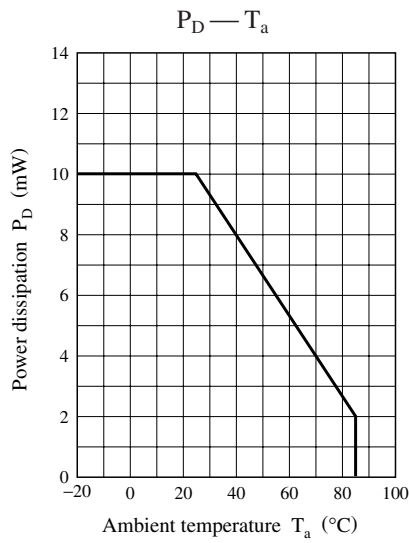
3. This device is designed be disregarded radiation.

4. *1: Source: Tungsten (color temperature 2856 K)

*2: Switching time measurement circuit



Note) The part number in the parenthesis shows conventional part number.



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